

# Electronic Thermal Management: Market Research Report

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## Abstracts

This report analyzes the worldwide markets for Electronic Thermal Management in US\$ Million by the following end-use segments: Computers, Telecom, Medical/Office Equipment, Industrial/Military, Consumer Electronics, and Automotive.

Also, the report provides market analytics for the Global and US market for the product segments - Hardware, Software, and Interfaces & Substrates.

Annual estimates and forecasts are provided for the period 2007 through 2015.

A six-year historic analysis is also provided for these markets.

The report profiles 158 companies including many key and niche players such as II-VI, Incorporated, Marlow Industries, Aavid Thermalloy, LLC, Advanced Thermal Solutions, Inc., Alcoa, Inc., Alpha Metals, Alpha Technologies Group, Inc., Ametek, Inc., Amkor Technology, Inc., Ansys, Inc., Ansoft Corporation, Fluent, Inc., ASAT Holdings Ltd., Brush Engineered Materials, Inc., Ceramics Process Systems Corporation, Chomerics, Comair Rotron, Inc., Cookson Electronics Assembly Materials, Cool Innovations, Inc., Cooler Master Co., Ltd., C-Therm Technologies Ltd., CTS Corporation, Daat Research Corp., Degree Controls, Inc., Dow Corning Corporation, Dynatron Corporation, Enertron, Inc., Ferraz Shawmut, LLC, Fujikura Ltd., Henkel Loctite Corporation, Honeywell Electronic Materials, Intricast Company Inc., ITW Vortec, JARO Components, Inc., Kooltronic, Inc., Kyocera Corporation, Laird Technologies, Liebert Corporation, Lord Corporation, Lytron Incorporated, Mentor Graphics Corporation, Metal Matrix Cast Composites, LLC, Micronel U.S., Netzsch Instruments, Inc., Netzsch Thermal Analysis, NMB Technologies Corporation, Noren Products, Inc., Orient Semiconductor Electronics Ltd., PC Power & Cooling, Inc., Pfannenber, Inc.,

PLANSEE Thermal Management Solutions, Sumitomo Electric Industries, Ltd., Tech Spray, L. P., Tellurex Corp., Tennmax United, The Bergquist Company, The Filter Factory, Inc., Thermacore, Transene Company, Inc., U.S. Toyo Fan Corporation, United Thermal Engineering Corporation, Vette Corp., and Wakefield Thermal Solutions, Inc.

Market data and analytics are derived from primary and secondary research.

Company profiles are mostly extracted from URL research and reported select online sources.

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Texas Instruments Takes Over Commergy Technologies  
Thermal Energy International Takes Over Gardner Energy Management  
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Vette Adds ERM  
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Ametek Adds Land Instruments  
Lytron Adds Lockhart Industries  
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Flomerics Acquires NIKA  
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Nextreme Inks License Deal with Caltech  
Celsia Signs Sales & Development Pact with Lighting Science  
Celsia Contracts with Kubo to Expand in Japan  
Hybricon and Parker Hannifin Sign Pact for Cooling Solutions  
Rogers and Thermal Transfer Composites Partner  
sp3 Partners with CPS



Celsia Teams Up with AET

Mathis Forms Distribution Partnership with Setaram Instrumentation

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II-VI, Incorporated (US)

Marlow Industries (US)

Aavid Thermalloy, LLC (US)

Advanced Thermal Solutions, Inc. (US)

Alcoa, Inc. (US)

Alpha Technologies, Inc. (US)

Ametek, Inc. (US)

Amkor Technology, Inc. (US)

Ansys, Inc. (US)

Ansoft Corporation (US)

Fluent, Inc. (US)

ASAT Holdings Ltd. (Hong Kong)

Brush Engineered Materials, Inc. (US)

Ceramics Process Systems Corporation (US)

Chomerics (US)

Comair Rotron, Inc. (US)

Cookson Electronics Assembly Materials (US)

Cool Innovations, Inc. (US)

Cooler Master Co., Ltd. (UK)

C-Therm Technologies Ltd. (Canada)

CTS Corporation (US)

Daat Research Corp. (US)

Degree Controls, Inc. (US)

Dow Corning Corporation (US)

Dynatron Corporation (US)

Enertron, Inc. (US)

Ferraz Shawmut, LLC (Canada)

Fujikura Ltd. (Japan)

Henkel Loctite Corporation (US)

Honeywell Electronic Materials (US)

Intricast Company Inc (US)

ITW Vortec (US)

JARO Components, Inc. (US)

Kooltronic, Inc. (US)

Kyocera Corporation (Japan)  
Laird Technologies (US)  
Liebert Corporation (US)  
Lord Corporation (US)  
Lytron Incorporated (US)  
Mentor Graphics Corporation (US)  
Metal Matrix Cast Composites, LLC (US)  
Micronel U.S. (US)  
Netzsch Instruments, Inc. (US)  
Netzsch Thermal Analysis (Germany)  
NMB Technologies Corporation (US)  
Noren Products, Inc. (US)  
Orient Semiconductor Electronics Ltd. (Taiwan)  
PC Power & Cooling, Inc. (US)  
Pfannenberg, Inc. (US)  
PLANSEE Thermal Management Solutions (US)  
Sumitomo Electric Industries, Ltd. (Japan)  
Tech Spray, L. P. (UK)  
Tellurex Corp. (US)  
Tennmax United (US)  
The Bergquist Company (US)  
The Filter Factory, Inc. (US)  
Thermacore (US)  
Transene Company, Inc. (US)  
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Total Companies Profiled: 158 (including Divisions/Subsidiaries - 178)

Region/Country/Players

The United States

Canada

Japan

Europe

France

Germany

The United Kingdom

Italy

Spain

Rest of Europe

Asia-Pacific (Excluding Japan)

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